IPC ASSOCIATION CONNECTINE ELECTRONICS INDUSTRIE	Material Composi © Copyright 2005. IPC international and Pan-A	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				e *	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					Ifg Informat	ion		
upplier Inform							123		,			8			
Company name* Company unique ID				Unique ID Authority			Response Date*								
nsemi											2023-06	2023-06-08			
Contact Name Tit				Title - Contact			Phone - Contact*				Email -	Email - Contact*			
Product-Env-Stewa	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
Authorized Representative* Title				itle - Representative			Phone - Representative*				Email -	Email - Representative*			
Product-Env-Stewards Product Enviro Compliance						NA				Product-Env-Stewards@onsemi.com					
Requeste	Requester Item Number Mfr Item		n Number Mfr Item Name			Effective Date	Version Manufacturing Site			Weight*	UOM	Unit Type			
		AR0237A A0-DPBR		2MP 1/3 CIS SO			2023-06-08		7	ГА1		235.62	mg	Each	
Ianufacturing	Proccess Informatio	n													
Terminal Plating / Grid Array Material Terminal Base Alloy			Alloy	J-STD-020 MS	L Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles						les				
SnAgCu		C	CU Alloy 3			260	260 C 30		secor	nds 3					
omments															
TTENTION: MSI	3 Rated item requires B	ake and Dr	ry Pack (after	electrical test)											
or more informati	on regarding material co	nposition p	olease refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).												
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the complance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.												
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted							
Exemption: If the declared item does not applicable exemptions.	contain RoHS restricted substances per t	he definition above except for defined Rol	IS exemptions, then select the corresponding	response in the R	oHS Declaration above and choose all							
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the							

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	35.27	mg		Misc.	proprietary data		0.134	mg
			Supplier	Silicon (Si)	7440-21-3		34.7868	mg
			Supplier	Aluminum (Al)	7429-90-5		0.3492	mg
Die Attach	2.27	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.8512	mg
			Supplier	Ethylene Glycol	107-21-1		0.0227	mg
			Supplier	Sulfonium (Thiodi-4,1-phenylene)	89452-37-9		0.0681	mg
			Supplier	Modified Silicon Dioxide (SiO2)	67762-90-7		0.4767	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.8512	mg
Imaging Lens	24.49	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		1.2889	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		1.2889	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		1.2889	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		0.1291	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		1.2889	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		1.2889	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		17.9164	mg
Lid Attach	1.34	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.4234	mg
			Supplier	Filler (SiO2)	68909-20-6		0.0697	mg
			Supplier	Epoxy Prepolymer	Proprietary Data		0.4234	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.4234	mg
Mold Compound-Black	60.82	mg		Phenolic Resin	proprietary data		9.123	mg
			Supplier	Oxirane	39817-09-9		9.123	mg
			Supplier	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8		1.8246	mg
			Supplier	Carbon Black (C)	1333-86-4		0.6082	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		38.9248	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		1.2164	mg
Solder Ball	45.55	mg	Supplier	Silver (Ag)	7440-22-4		1.3665	mg
			Supplier	Tin (Sn)	7440-31-5		43.9557	mg
			Supplier	Copper (Cu)	7440-50-8		0.2277	mg
Substrate and Solder Mask	65.37	mg	В	Nickel (Ni)	7440-02-0		2.6148	mg
			Supplier	Gold (Au)	7440-57-5		0.2615	mg
			Supplier	Cured Resin of Solder Mask	Proprietary Data		15.6888	mg
			Supplier	Bismaleimide Triazine resin	Proprietary Data		39.222	mg

			Supplier	Copper (Cu)	7440-50-8	7.5829	mg
Wire Bond - Au	0.51	mg	Supplier	Gold (Au)	7440-57-5	0.51	mg